## nexperia

## **Quarterly Reliability Monitoring Results**

Quarters: Q1/2022 to Q4/2023 Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number						
		PMEG1020EH-Q						
		Part Description						
		Nexperia DHAM Schottky						
		SMD package						
		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
	TEST							
	Pre- and Post-Stress							
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
// L1		JESD22-A113	,					
		Bake Tamb = 125 °C	24 hours					
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours					
# A1	Preconditioning	Reflow soldering	3 cycles	1514	64430	0		
	5	MIL-STD-750-1	•					
	HTRB	M1038 Method A						
		Tj = Tjmax, Vr = 100% of max. datasheet						
# B1	Bias	reverse voltage <sup>[1]</sup>	1000 hours	206	9320	0		
	тс	JESD22-A104						
# A4	Temperature Cycling	-65 °C to Timax, not to exceed 150°C	1000 cycles	311	14080	0		
	. , , ,					-		
	UHAST	JESD22-A118						
# A3 <b>or</b>	Unbiased HAST	Tamb = 130 °C, RH = 85 %						
		JESD22-A102	— 96 hours	311	14080	0		
	AC	Tamb = $121 ^{\circ}C$ , RH = $100 ^{\circ}M$						
# A3 alt	Autoclave	Pressure = $205 \text{ kPa} (29.7 \text{ psia})$						
	H3TRB	JESD22-A101						
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of						
# A2 alt	Temperature Reverse Bias		1000 hours	311	14080	0		
		MIL-STD-750 Method 1037	2000 1100/3	511	1000	~		
	IOL	ton = toff, devices powered to insure $\Delta T_i$ =						
# A5	Intermittent Operating Life		1000 hours	312	14120	0		
# AJ			2000 1100/3	512	- 1120	-		
	RSH	JESD22-A111						
# C8	Resistance to Solder Heat	$260 \circ C \pm 5 \circ C$	10 s	269	8070	0		
# C8	SD	200 0 - 5 0	10.3	205	5575	5		
	Solderability	J-STD-002		222	6660	0		
	,	des have to be considered (thermal runaway).		222	0000	U		

The physical limitations of Schottky diodes have to be considered (thermal runaway).
The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Schottky	9320	0	0,46	2,19E+09

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